
CLEAN COPY OF AMENDED CLAIMS:

1. A method of making at least one resistor, the method comprising:

providing a sacrificial layer having a first surface and one or more pads including at least one electrically conductive material disposed over at least one region of said first surface;

depositing an electrically resistive material over said pads and over said first surface of said sacrificial layer to thereby form at least one unit including said electrically resistive material and said one or more pads;

removing at least a portion of said sacrificial layer to expose said one or more pads.

2. The method as claimed in claim 1, wherein a plurality of resistors is manufactured simultaneously using a single sacrificial layer, the method further comprising separating at least some of said resistors from one another after at least a portion of the sacrificial layer has been removed.

6. The method as claimed in claim 5 wherein said step of providing said cavities in said first surface includes providing an apertured layer on said first surface and etching said first surface through apertures in said apertured layer.

10. The method as claimed in claim 6, further comprising removing at least a portion of said apertured layer from said first surface of said sacrificial layer.

18. The method as claimed in claim 16 wherein said step of depositing said electrically resistive material is performed so as to embed one flange and at least a part of the post of each said pad in the electrically resistive material while leaving at least part of the other flange of each said pad exposed at a surface of said electrically resistive material.

22. The method as claimed in claim 1, further comprising removing excess electrically resistive material from each said unit using a bulk trimming process.

23. The method as claimed in claim 1, further comprising providing a heat sink having a first surface wherein said electrically resistive material forms an electrically resistive layer having a first surface and a second surface, wherein said first surface of said electrically resistive layer is connected to said first surface of said heat sink.

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24. The method as claimed in claim 1, further comprising before depositing said electrically resistive material, providing an insulating layer having a first surface and a second surface, wherein said electrically resistive material is deposited between said second surface of said insulating layer and said first surface of said sacrificial layer.

25. The method as claimed in claim 24, wherein a plurality of resistors are manufactured simultaneously using a single sacrificial layer and a common insulating layer, the method further comprising separating at least some of said resistors from one another after removing at least a portion of the sacrificial layer, wherein said separated resistors remain connected to said common insulating layer.

26. The method as claimed in claim 1, further comprising trimming said electrically resistive material in at least one said unit to control electrical resistance of at least one said unit.

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29. A method of making at least one resistor, the method comprising:

providing a sacrificial layer having a first surface
and a plurality of cavities in the first surface
of said sacrificial layer;

depositing one or more conductive materials within said cavities to form conductive pads within said cavities;

disposing an electrically resistive material over the first surface of the sacrificial layer and the pads to thereby form one or more units; and

removing at least a portion of said sacrificial layer to expose said pads.

30. The method of claim 29 wherein said step of depositing one or more conductive materials is performed so as to form said pads as hollow shells within said cavities, and wherein said step of disposing electrically resistive material includes applying said electrically resistive material into said hollow shells.

31. The method as claimed in claim 29, wherein a plurality of resistors are manufactured simultaneously using the same sacrificial layer, the method further comprising a step of separating at least some of the resistors from one another after at least a portion of the sacrificial layer has been removed.

35. The method as claimed in claim 33, further comprising removing at least a portion of said apertured layer from said first surface of the sacrificial layer before depositing said electrically resistive material.

36. The method as claimed in claim 35, wherein all of said patternable layer is removed from the first surface of the sacrificial layer before depositing said electrically resistive material.

37. The method as claimed in claim 29, further comprising, before depositing said electrically resistive material, providing an insulating layer having a first surface and a second surface, wherein said resistive material is deposited between said second surface of said insulating layer and said first surface of said sacrificial layer.

38. A method of making at least one resistor, the method comprising:

providing a sacrificial layer having a first surface and a second surface;

depositing an electrically resistive material over said first surface of said sacrificial layer so that said resistive material adheres to said sacrificial layer; and

selectively removing portions of said sacrificial layer to form one or more pads connected to said resistive material.

39. A method as claimed in claim 38 wherein said first surface of said sacrificial layer is rough, and the roughness of said first surface promotes adhesion between said sacrificial layer and said electrically resistive material.

42. The method as claimed in claim 38, further comprising before depositing said electrically resistive material, providing an insulating layer having a first surface and a second surface, wherein said resistive material is deposited between said second surface of said insulating layer and said first surface of said sacrificial layer.